ON Semiconductor®

FDS6975

Dual P-Channel, Logic Level, PowerTrench™ MOSFET

General Description

These P-Channel Logic Level MOSFETs are produced using ON Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

These devices are well suited for notebook computer applications: load switching and power management, battery charging circuits, and DC/DC conversion.

Features

- -6 A, -30 V. $R_{DS(ON)} = 0.032\ \Omega$ @ $V_{GS} = -10$ V, $R_{DS(ON)} = 0.045\ \Omega$ @ $V_{GS} = -4.5$ V.

- Low gate charge (14.5nC typical).

- High performance trench technology for extremely low $R_{DS(ON)}$.

- High power and current handling capability.
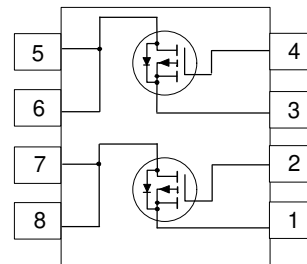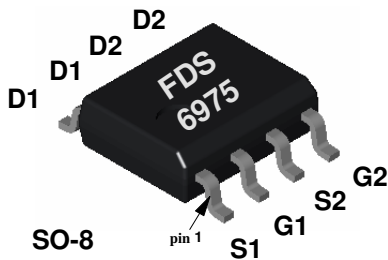
SOT-23	SuperSOT™-6	SuperSOT™-8	SO-8	SOT-223	SOIC-16

Absolute Maximum Ratings $T_A = 25^\circ C$ unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		-30	V
V_{GSS}	Gate-Source Voltage		±20	V
I_D	Drain Current - Continuous	(Note 1a)	-6	A
	- Pulsed		-20	
P_D	Power Dissipation for Dual Operation		2	W
	Power Dissipation for Single Operation	(Note 1a)	1.6	
		(Note 1b)	1	
		(Note 1c)	0.9	
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to 150	°C
THERMAL CHARACTERISTICS				
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)		78	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)		40	°C/W

**Electrical Characteristics** (T_A = 25 ^{O}C unless otherwise noted)

| Symbol	Parameter	Conditions		Min	Typ	Max	Units
OFF CHARACTERISTICS							
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = -250 μA		-30			V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	I_D = -250 μA, Referenced to 25 °C			-21		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = -24 V, V_{GS} = 0 V				-1	μA
			T_J = 55°C			-10	μA
I_{GSSF}	Gate - Body Leakage, Forward	V_{GS} = 20 V, V_{DS} = 0 V				100	nA
I_{GSSR}	Gate - Body Leakage, Reverse	V_{GS} = -20 V, V_{DS} = 0 V				-100	nA
ON CHARACTERISTICS (Note 2)							
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = -250 μA		-1	-1.7	-3	V
$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Temp. Coefficient	I_D = 250 μA, Referenced to 25 °C			4		mV/°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS} = -10 V, I_D = -6 A			0.025	0.032	Ω
			T_J =125°C		0.033	0.051	
		V_{GS} = -4.5 V, I_D = -5 A			0.034	0.045	
$I_{D(ON)}$	On-State Drain Current	V_{GS} = -10 V, V_{DS} = -5 V		-20			A
g_{FS}	Forward Transconductance	V_{DS} = -10 V, I_D = -6 A			16		S
DYNAMIC CHARACTERISTICS							
C_{iss}	Input Capacitance	V_{DS} = -15 V, V_{GS} = 0 V, f = 1.0 MHz			1540		pF
C_{oss}	Output Capacitance				400		pF
C_{rss}	Reverse Transfer Capacitance				170		pF
SWITCHING CHARACTERISTICS (Note 2)							
$t_{D(on)}$	Turn - On Delay Time	V_{DS} = -15 V, I_D = -1 A			13	24	ns
t_r	Turn - On Rise Time	V_{GEN} = -10 V, R_{GEN} = 6 Ω			22	35	ns
$t_{D(off)}$	Turn - Off Delay Time				47	75	ns
t_f	Turn - Off Fall Time				18	30	ns
Q_g	Total Gate Charge	V_{DS} = -10 V, I_D = -6 A, V_{GS} = -5 V			14.5	20	nC
Q_{gs}	Gate-Source Charge				4		nC
Q_{gd}	Gate-Drain Charge				5		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS							
I_S	Maximum Continuous Drain-Source Diode Forward Current					-1.3	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0 V, I_S = -1.3 A (Note 2)			-0.73	-1.2	V

Notes:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.
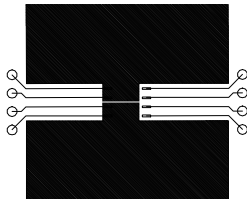
a. 78°C/W on a 0.5 in^2 pad of 2oz copper.
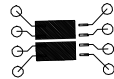
b. 125°C/W on a 0.02 in^2 pad of 2oz copper.
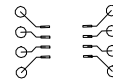
c. 135°C/W on a 0.003 in^2 pad of 2oz copper.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width $\leq$ 300μs, Duty Cycle $\leq$ 2.0%.
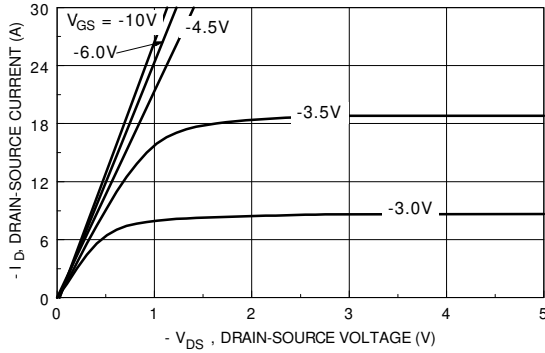
Typical Electrical Characteristics
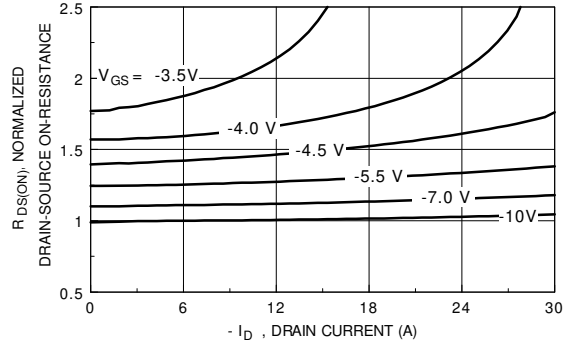

Figure 1. On-Region Characteristics.

Figure 2. On-Resistance Variation with Dain Current and Gate Voltage.
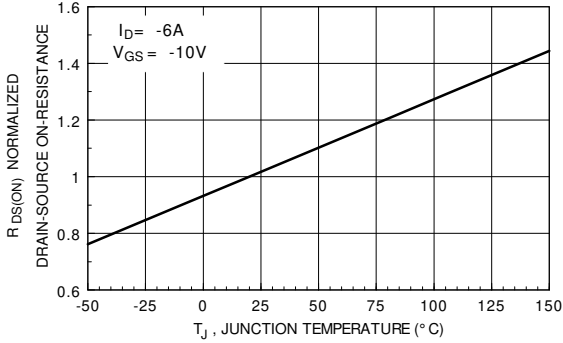

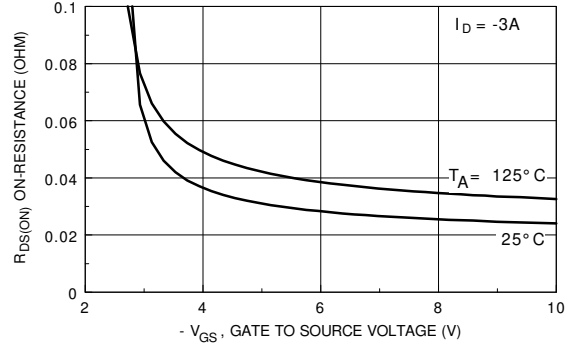Figure 3. On-Resistance Variation with Temperature.

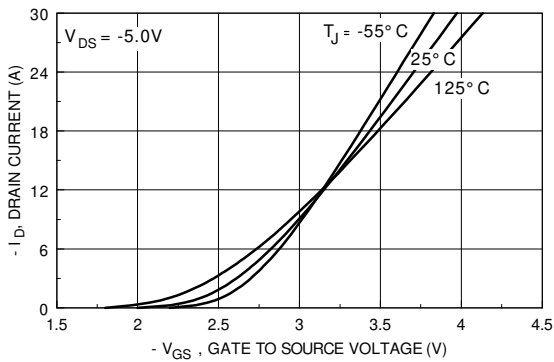Figure 4. On-Resistance Variation with Gate-to-Source Voltage.
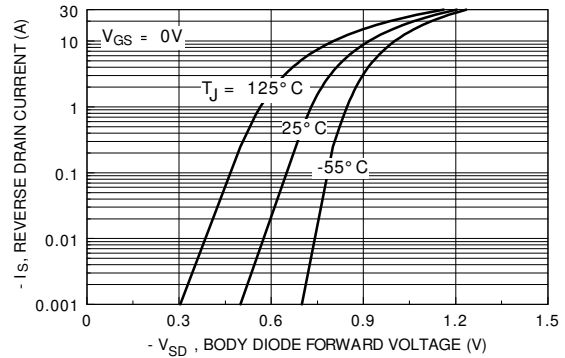

Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.
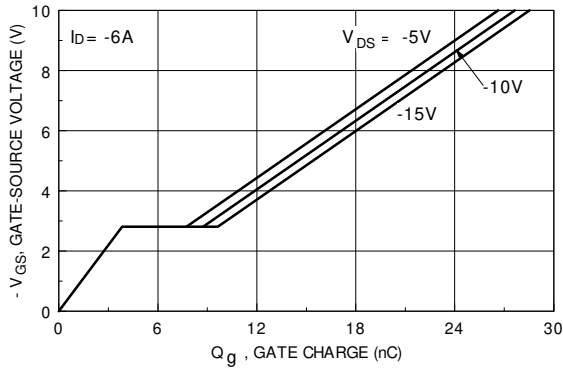
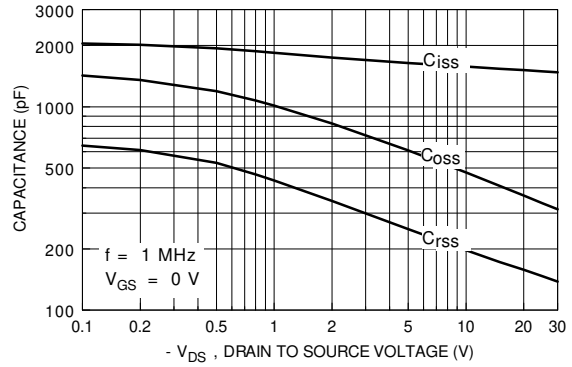## Typical Electrical Characteristics (continued)

Figure 7. Gate Charge Characteristics.

Figure 8. Capacitance Characteristics.
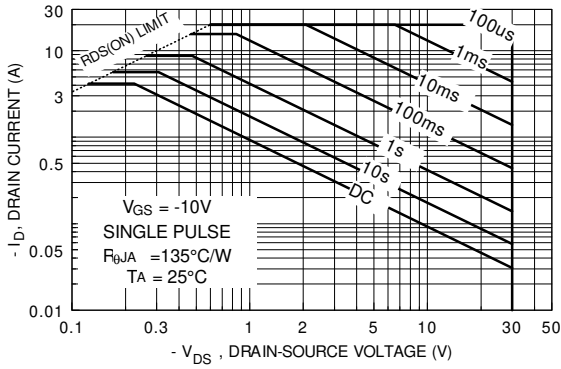
Figure 9. Maximum Safe Operating Area.
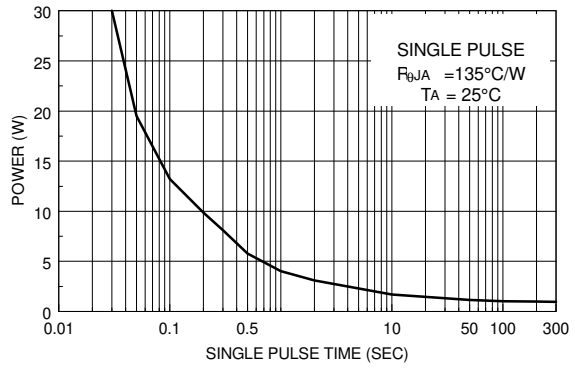
Figure 10. Single Pulse Maximum Power Dissipation.
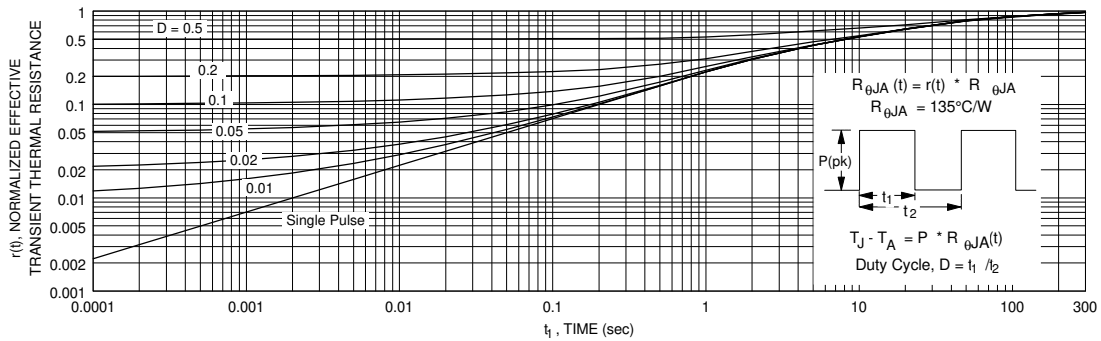
Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c.
Transient thermal response will change depending on the circuit board design.

PUBLICATION ORDERING INFORMATION

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